



LNP™ THERMOCOMP™ Compound LC008EXQ

Americas: COMMERCIAL

Also known as: LNP™ THERMOCOMP™ Compound LC008EXQ

Product reorder name: LC008EXQ

LNP THERMOCOMP LC008EXQ is a compound based on Polyetheretherketone containing 40% Carbon Fiber. Added features of this grade include: Electrically Conductive, Easy Molding.

TYPICAL PROPERTIES ¹	TYPICAL VALUE	Unit	Standard
MECHANICAL			
Tensile Stress, brk, Type I, 5 mm/min	3360	kgf/cm ²	ASTM D 638
Tensile Strain, brk, Type I, 5 mm/min	1.5	%	ASTM D 638
Tensile Modulus, 5 mm/min	422900	kgf/cm ²	ASTM D 638
Flexural Stress, brk, 1.3 mm/min, 50 mm span	5010	kgf/cm ²	ASTM D 790
Flexural Modulus, 1.3 mm/min, 50 mm span	358900	kgf/cm ²	ASTM D 790
Tensile Stress, break, 5 mm/min	321	MPa	ISO 527
Tensile Strain, break, 5 mm/min	1.4	%	ISO 527
Tensile Modulus, 1 mm/min	40420	MPa	ISO 527
Flexural Stress	460	MPa	ISO 178
Flexural Modulus, 2 mm/min	33820	MPa	ISO 178
Compressive Strength	215	MPa	SABIC Method
Shear Strength	1284	kgf/cm ²	ASTM C 273
Shear Modulus	51010	kgf/cm ²	ASTM C 273
IMPACT			
Izod Impact, unnotched, 23°C	88	cm-kgf/cm	ASTM D 4812
Izod Impact, notched, 23°C	8	cm-kgf/cm	ASTM D 256
Instrumented Impact Total Energy, 23°C	73	cm-kgf	ASTM D 3763
THERMAL			
HDT, 1.82 MPa, 3.2mm, unannealed	335	°C	ASTM D 648
PHYSICAL			
Specific Gravity	1.44	-	ASTM D 792
Moisture Absorption, 50% RH, 24 hrs	0.05	%	ASTM D 570
Mold Shrinkage, flow, 24 hrs (5)	0.15 - 0.3	%	ASTM D 955
Mold Shrinkage, xflow, 24 hrs (5)	0.7 - 1.4	%	ASTM D 955



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TYPICAL PROPERTIES ¹	TYPICAL VALUE	Unit	Standard
ELECTRICAL Surface Resistivity	1.E+02 - 1.E+03	Ohm	ASTM D 257



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PROCESSING PARAMETERS	TYPICAL VALUE	Unit
Injection Molding		
Drying Temperature	150	°C
Drying Time	4 - 6	hrs
Front - Zone 3 Temperature	380 - 400	°C
Middle - Zone 2 Temperature	380 - 400	°C
Rear - Zone 1 Temperature	370 - 380	°C
Mold Temperature	175 - 190	°C
Back Pressure	0.3 - 0.7	MPa
Screw Speed	60 - 100	rpm